

PATENT

**IN THE U.S. PATENT AND TRADEMARK OFFICE**

In re application of: **Masanao Hori**  
Appl. No.:  Conf.:   
Filed: **August 13, 2003** Group:   
Title: **FABRICATION METHOD FOR A SEMICONDUCTOR  
CSP TYPE PACKAGE** Examiner:

**PRELIMINARY AMENDMENT**

Assistant Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

August 13, 2003

Sir:

The following preliminary amendments and remarks are respectfully submitted in connection with the above-identified application.

**Amendments to the Specification** begin on page 2 of this paper.

**Remarks** begin on page 3 of this paper.

An **Appendix** is attached following the signature page of this paper.